

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

1-16. (cancelled)

17. (previously presented) A product (10) usable as a starting substrate for the manufacture of micro-electronic and/or micro-mechanic devices, comprising

wafer (10) of a semi-conducting or conducting material, and having a first (14) and a second (16) surface;

at least one electrically conducting member (12) extending through said wafer,

characterized in that

the electrically conducting member (12) is insulated from surrounding material of the wafer by a finite layer (15) of an insulating material; and in that

it comprises the same material as the wafer, i.e. it is made from the wafer material.

18. (previously presented) The product as claimed in claim 17, wherein said wafer is a semiconductor wafer.

19. (previously presented) The product as claimed in claim 18, wherein said wafer is a silicon wafer.

20. (previously presented) The product as claimed in claim 17, wherein said wafer has a thickness of 200 - 5000 μm , preferably 300 - 3000 μm , most preferably 400 - 1000 μm .

21. (previously presented) The product as claimed in claim 17, wherein the thickness of the finite layers of insulating material is 1-20 μm , typically 8-12 μm .

22. (previously presented) The product as claimed in claim 17, wherein the pitch/center-to-center distance between the electrical connections is larger than 10 μm , typically 50-100 μm .

23. (previously presented) The product as claimed in claim 17, wherein the wafer is essentially flat.

24. (previously presented) The product as claimed in claim 17, wherein the wafer comprises one or more local depressions (75) in at least one surface thereof, wherein the insulated electrical connections are essentially flush with the bottom surface of said depressions.

25. (previously presented) A Micro-Electrical-Mechanical System (MEMS) device, comprising solder bumps for flip-chip mounting placed on the backside of the device, and having wafer through electrical interconnections (vias, 12),

wherein the electrical interconnections (12) are insulated from surrounding material of the wafer by a finite layer (15) of an insulating material, wherein the material of the interconnections comprise the same material as the wafer, i.e. it is made from the wafer material.

26-27. (cancelled)